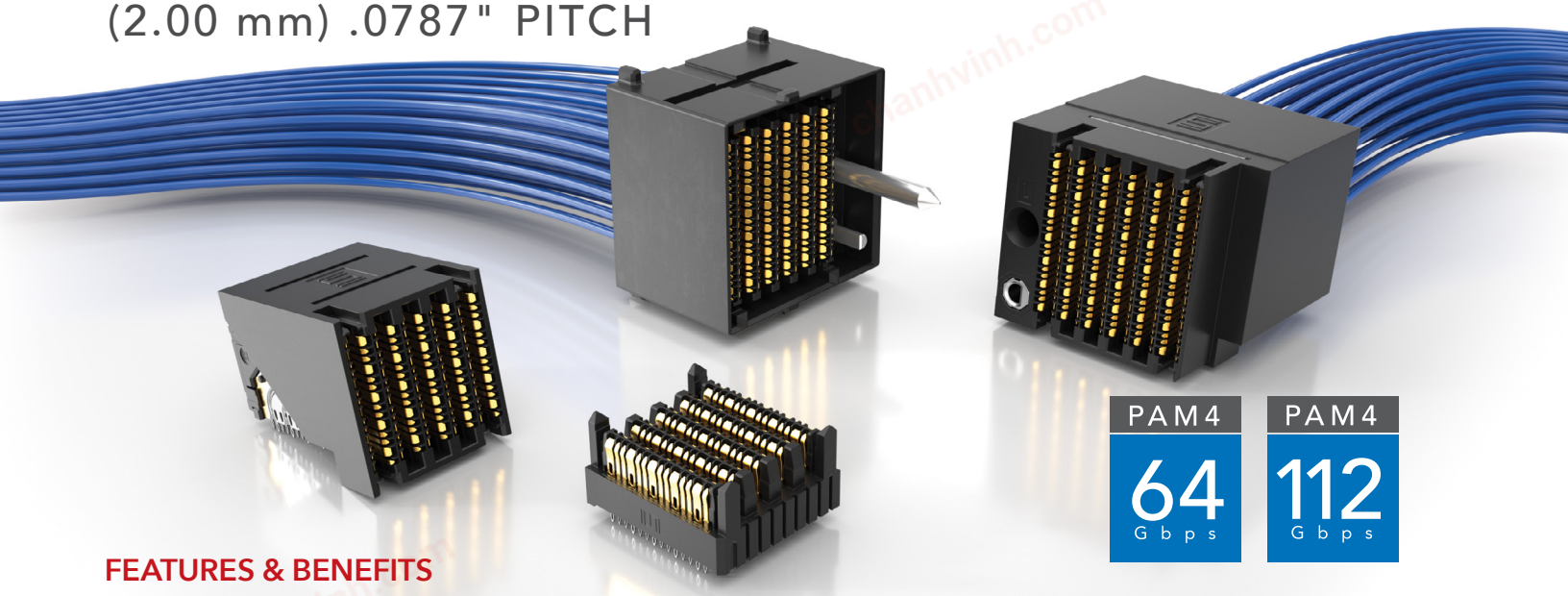
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ExaMAX®

HIGH-SPEED BACKPLANE CONNECTOR & CABLE SYSTEMS

(2.00 mm) .0787" PITCH



PAM4 64 Gbps

PAM4 112 Gbps

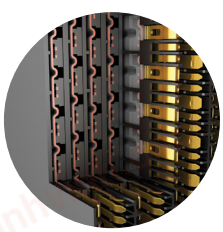
FEATURES & BENEFITS

ExaMAX® High-Speed Backplane System

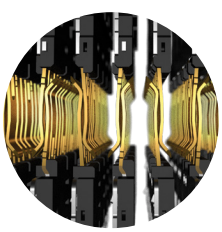
- Meets a variety of industry specifications
- Traditional, coplanar and direct mate orthogonal
- 24 - 72 pair designs (4 and 6 pairs; 6, 8, 10 and 12 columns)
- Shielded wafer design reduces crosstalk and includes one sideband signal per column
- Press-fit tails provide a reliable electrical connection
- PCIe® 6.0/CXL® 3.2 capable

ExaMAX® High-Speed Backplane Cable Assemblies

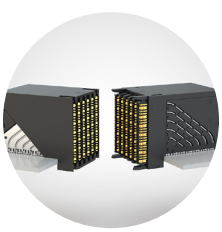
- 30 & 34 AWG Eye Speed® ultra low skew twinax cable
- 34 AWG Eye Speed Thinax™ ultra low skew twinax cable
- Offers improved signal integrity, increased flexibility and routability
- Highly customizable with modular flexibility
- Reduce costs due to lower layer counts
- PCIe® 6.0/CXL® 3.2 capable



Staggered Differential Pair Design



Two Reliable Points of Contact with a 2.4 mm Wipe



In Development: Open-Pin-Field, Coplaner Configuration



In Development: 2 Pair Design for a Lower Profile



In Development: ExaMAX2® 8 Pairs for 112 Gbps PAM4 Performance

KEY SPECIFICATIONS

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
EBTM/EBTF/EBDM	Liquid Crystal Polymer	Copper Alloy	Sn or Au over 50 µ" (1.27 µm) Ni	-55 °C to +105 °C	4 A per pin	150 VAC/212 VDC	Yes
EPTT/EPTS	High Temperature Thermoplastic	Copper Alloy	Sn or Au over 50 µ" (1.27 µm) Ni	-55 °C to +105 °C	14.1 A per pin	150 VAC/212 VDC	Yes
EBCM/EBCF	Liquid Crystal Polymer	Copper Alloy	Au over 50 µ" (1.27 µm) Ni	-40 °C to +105 °C	2.6 A per pin	125 VAC/177 VDC	N/A

PCI-SIG®, PCI Express® and the PCIe® design marks are registered trademarks and/or service marks of PCI-SIG.

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.

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ExaMAX®

ExaMAX® POWER MODULES

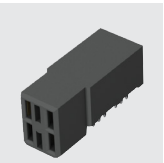
(2.00 mm) .0787" PITCH TERMINAL POWER MODULES



EPTT
Mates with:
EPTS

EPTT	–	POSITIONS PER ROW	–	PLATING	–	HEIGHT	–	D	–	ORIENTATION
		–2 = 4 Positions		**–P** = Palladium with flash Gold on contacts, Matte Tin on tails		**–11.5** = (11.50 mm) .453"				**–RA** = Right-Angle

(2.00 mm) .0787" PITCH SOCKET POWER MODULES



EPTS
Mates with:
EPTT

EPTS	–	POSITIONS PER ROW	–	PLATING	–	D	–	ORIENTATION	–	PIN STAGING
		–2 = 4 Positions		**–P** = Palladium with flash Gold on contacts, Matte Tin on tails				**–VT** = Vertical **–RA** = Right-Angle		Visit website for dimensions. **–01 thru –06** (Vertical) **-04 & -08** (Right-Angle)

View complete specifications at: **samtec.com?EPTT & samtec.com?EPTS**

ExaMAX® GUIDE MODULES

TERMINAL GUIDE MODULES



EGBM
Mates with:
EGBF
Insulator Material:
Zinc Alloy

EGBM	–	ORIENTATION	–	THREADING	–	LENGTH	–	CARD SPACING
		–VT = Vertical **–RA** = Right-Angle		Leave Blank for -RA **–1** = External **–2** = Internal (25.3 Length only)		Leave Blank for -RA **–18.3** = 18.30 mm (.720") **–25.3** = 25.30 mm (.996")		**–20** = 20 mm (.787")

SOCKET GUIDE MODULES



EGBF
Mates with:
EGBM
Insulator Material:
Zinc Alloy

EGBF	–	ORIENTATION	–	CARD SPACING
		–RA = Right-Angle		**–20** = 20 mm (.787")

Notes:
Some lengths, styles and options are non-standard, non-returnable.

ExaMAX® is a registered trademark of AFCI.

View complete specifications at: **samtec.com?EGBM & samtec.com?EGBF**

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.